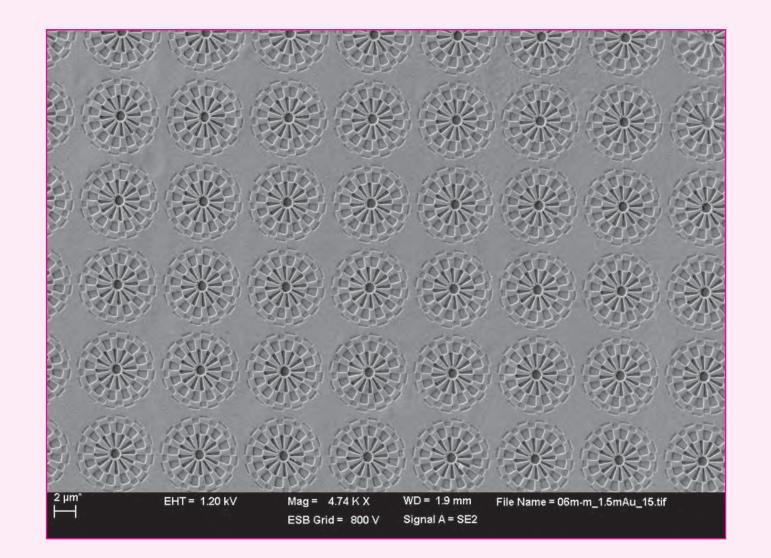
micro resist technology GmbH Köpenicker Straße 325 12555 Berlin Germany Tel.: +49 (0) 30 641670100 Fax: +49 (0) 30 641670200 info@microresist.de www.microresist.com



# mr-XNIL26SF – A Fluorine modified UV nanoimprint resist with advanced release properties

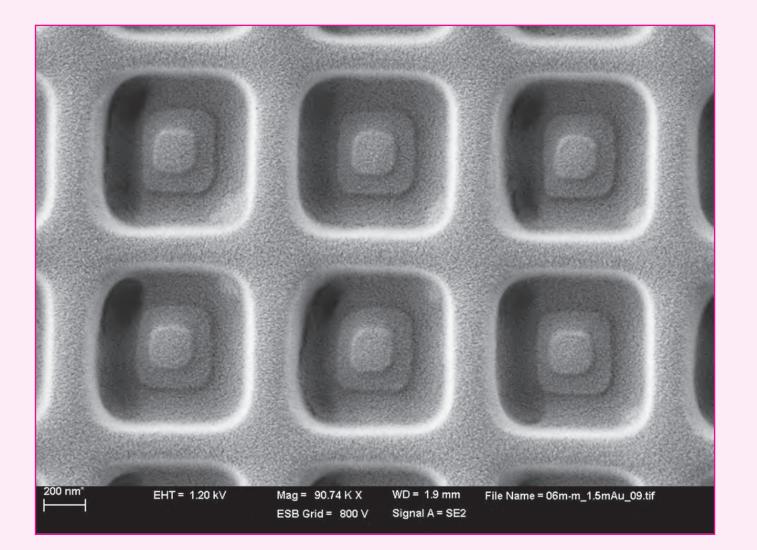
mr-XNIL26SF can be applied as single layer resist without any adhesion layer on a variety of substrates like Si, glass, plastics, metals, etc. The fluorinated components facilitate the demolding step and also increase the lifetime of anti-sticking layers.



### **Resist characteristics**

**Excellent release due to fluorinated components** 

SEM micrographs of imprints with solvent-free mr-XNIL26SF (Courtesy of N. Kehagias, Nanofabrication Division, Catalan Institute of Nanotechnology)



- <sup>–</sup> Very good wetting and adhesion on various substrates without adhesion promoter due to the oligomeric components
- Fast curing and high resolution
- Fully organic material (no Silicon)
- Can be diluted down to 100 nm

## **Exemplary application fields**

- Etch mask for wet-chemical etch processes or for RIE pattern transfer
- Fabrication of micro/nano-scale patterns with high aspect ratio
- **Top-layer for multilayer material stacks**

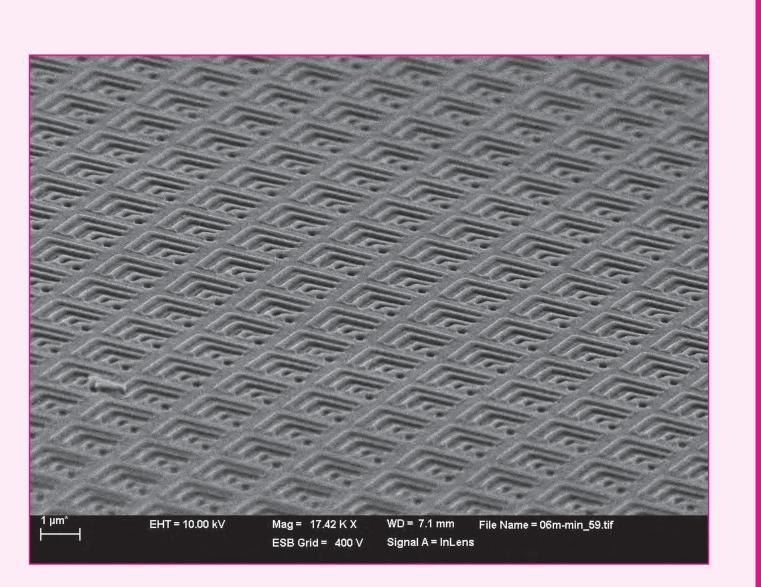
## **Availability**

Ducalit

Film thickness 

### **Recommended processing parameters**

SEM micrographs of imprints with solvent-free mr-XNIL26SF (Courtesy of N. Kehagias, Nanofabrication Division, Catalan Institute of Nanotechnology)



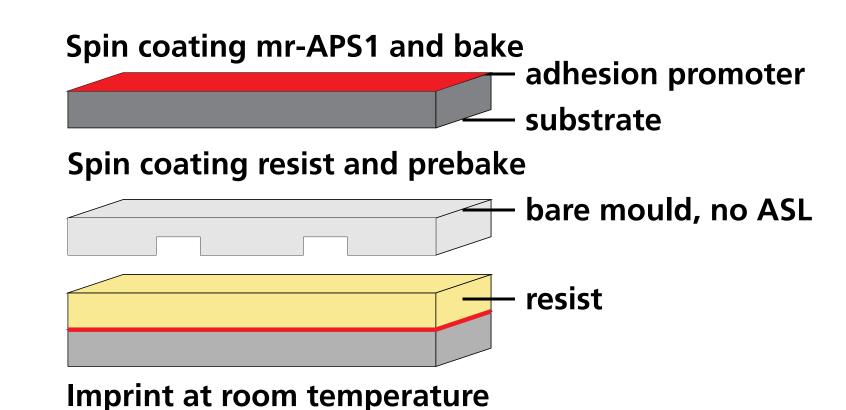
SEM micrographs of imprints with solvent-free mr-XNIL26SF (Courtesy of N. Kehagias, Nanofabrication Division, Catalan Institute of Nanotechnology)

Product	FIIM THICKNESS "
mr-XNIL26SF	4800 ± 200 nm

<sup>a)</sup> Layer preparation by spin-coating @ 3000 rpm

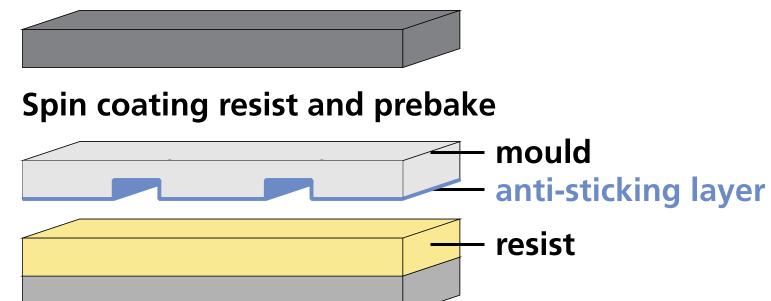
Process step	Process parameter
Spin-coating	3000 rpm for 30 s
Softbake conditions	60-80 °C for 1 min
Imprint temperature	Room temperature
Imprint pressure	0.1 – 10 bars
Exposure dose	> 220 mJ/cm2
Mould release	Room temperature
Resist thinner	ma-T 1050

**Option 1** 

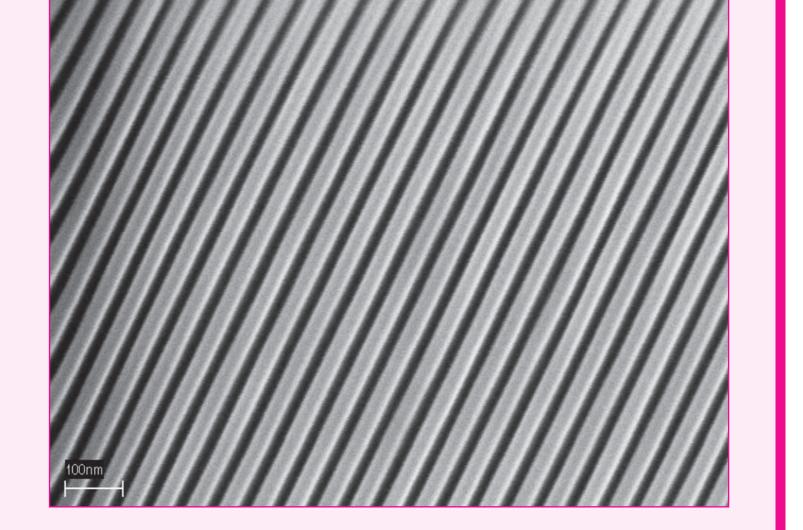


**Option 2** 

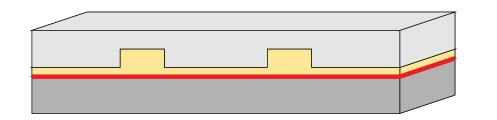
**Bare substrate** 

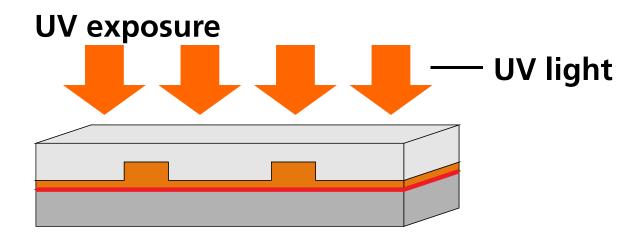


#### Imprint at room temperature

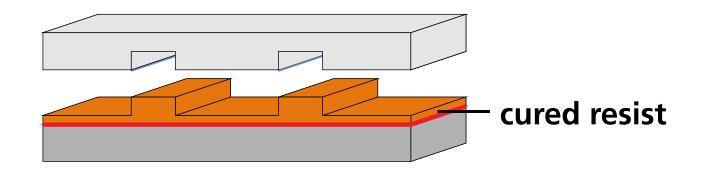


SEM image of 15 nm trenches and 50 nm bars imprinted into a layer of glass substrate. Si mould was provided by Eulitha AG. ASL: F13-TCS. Pattern depth: ~50 nm (Courtesy of PSI, Switzerland. Scale: 100 nm)

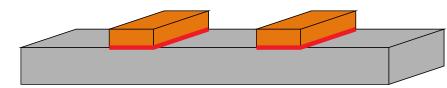


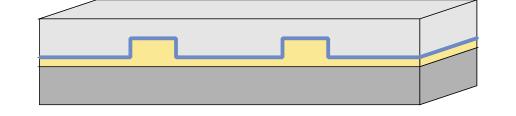


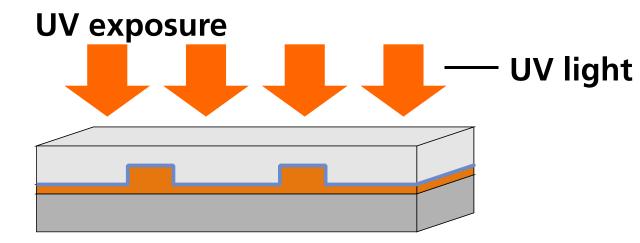
#### Mould release



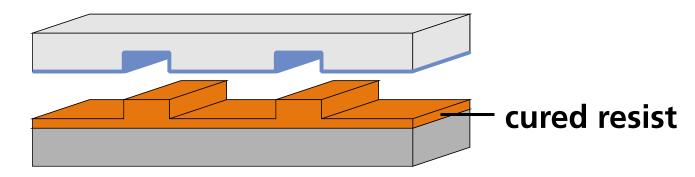
#### Anisotropic plasma etch







#### **Mould release**



#### Anisotropic plasma etch

